

GB01SHT12-CAU

Silicon Carbide Power Schottky Diode Chip

Features

- 1200 V Schottky rectifier
- 250 °C maximum operating temperature
- Temperature independent switching behavior
- Superior surge current capability
- Positive temperature coefficient of V_F
- Extremely fast switching speeds
- Superior figure of merit Q_C/I_F



Maximum Ratings at T_i = 250 °C, unless otherwise specified

Parameter	Symbol	Conditions	Values	Unit
Repetitive peak reverse voltage	V _{RRM}		1200	V
Continuous forward current	l _F	T _C ≤ 235 °C	1	А
RMS forward current	I _{F(RMS)}	T _C ≤ 235 °C	2	А
Operating and storage temperature	T _j , T _{stg}		-55 to 250	°C

Electrical Characteristics at T_j = 250 °C, unless otherwise specified

Parameter	Symbol	Conditions -		Values		11	
				min.	typ.	max.	Unit
Diode forward voltage	V _F	I _F = 1 A, T _j = 25 °C I _F = 1 A, T _i = 210 °C		1.96 3.1		V	
Reverse current	I _R	V _R = 1200 V, T _j = 25 °C V _R = 1200 V, T _i = 275 °C		0.1 6.6	10 30	μA	
Total capacitive charge	Qc	$ _{F} \leq _{F,MAX}$	V _R = 400 V V _R = 960 V		6 11		nC
Switching time	ts	dl _F /dt = 200 A/µs T _j = 210 °C	V _R = 400 V V _R = 960 V		< 17		ns
Total capacitance	С	V _R = 1 V, f = 1 MHz V _R = 400 V, f = 1 MH V _R = 1000 V, f = 1 MH	z, T _j = 25 °C		66 10 8		pF

Thermal Characteristics

Thermal resistance, junction - case	R _{thJC}	Assuming TO-276 package	3.55	°C/W

*For chip size and metallization, please refer to the mechanical datasheet (must have a non-disclosure agreement with GeneSiC Semiconductor).

Electrical Datasheet*

GB01SHT12-CAU

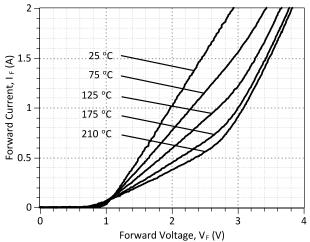


Figure 1: Typical Forward Characteristics

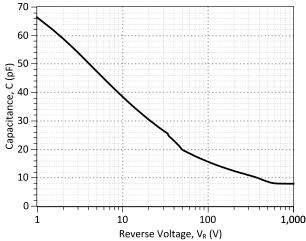


Figure 3: Typical Junction Capacitance vs Reverse Voltage Characteristics

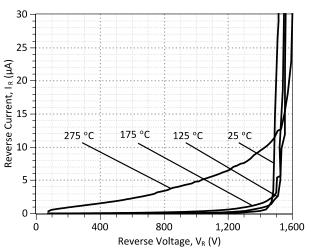
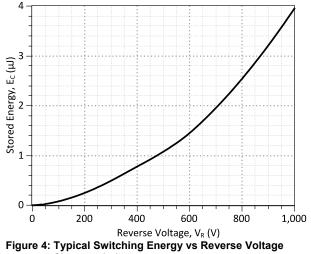


Figure 2: Typical Reverse Characteristics



Characteristics

Revision History					
Date	Revision	Comments	Supersedes		
2012/04/03	0	Initial release			

Published by GeneSiC Semiconductor, Inc. 43670 Trade Center Place Suite 155 Dulles, VA 20166

GeneSiC Semiconductor, Inc. reserves right to make changes to the product specifications and data in this document without notice.

GeneSiC disclaims all and any warranty and liability arising out of use or application of any product. No license, express or implied to any intellectual property rights is granted by this document.

Unless otherwise expressly indicated, GeneSiC products are not designed, tested or authorized for use in life-saving, medical, aircraft navigation, communication, air traffic control and weapons systems, nor in applications where their failure may result in death, personal injury and/or property damage.



SPICE Model Parameters

Copy the following code into a SPICE software program for simulation of the GB01SHT12-CAU device.

```
*
     MODEL OF GeneSiC Semiconductor Inc.
*
*
     $Revision: 1.0
                                $
*
     $Date: 05-SEP-2013
                                $
*
    GeneSiC Semiconductor Inc.
*
*
     43670 Trade Center Place Ste. 155
*
    Dulles, VA 20166
*
    httphttp://www.genesicsemi.com/index.php/sic-products/schottky
*
*
    COPYRIGHT (C) 2013 GeneSiC Semiconductor Inc.
*
     ALL RIGHTS RESERVED
* These models are provided "AS IS, WHERE IS, AND WITH NO WARRANTY
* OF ANY KIND EITHER EXPRESSED OR IMPLIED, INCLUDING BUT NOT LIMITED
* TO ANY IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A
* PARTICULAR PURPOSE."
* Models accurate up to 2 times rated drain current.
* Start of GB01SHT12-CAU SPICE Model
.SUBCKT GB01SHT12 ANODE KATHODE
R1 ANODE INT R=((TEMP-24)*0.0099); Temperature Dependant Resistor
D1 INT KATHODE GB01SHT12 25C; Call the 25C Diode Model
D2 ANODE KATHODE GB01SHT12 PIN; Call the PiN Diode Model
.MODEL GB01SHT12 25C D
     1.88E-18
+ IS
                                     0.9255
                          RS
+ N
         1
                         IKF
                                     98.29122743
         1.2
+ EG
                         XTI
                                     3
+ CJO
                                     0.367
         7.90E-11
                         VJ
+ M
         1.63
                          FC
                                     0.5
+ TT
        1.00E-10
1.00E-03
                          ΒV
                                     1500
+ IBV
                         VPK
                                    1200
+ IAVE
                                    SiC Schottky
         1
                          TYPE
+ MFG GeneSiC Semiconductor
.MODEL GB01SHT12 PIN D
         2.76E-16
                                    0.84243
+ IS
                          RS
+ N
         3.791461
                         IKF
                                    2.98675
+ EG
         3.23
                         XTI
                                    30
+ FC
          0.5
                         TT
                                     0
+ BV
         1500
                         IBV
                                    1.00E-03
+ VPK
         1200
                          IAVE
                                     1
+ TYPE SiC_PiN
.ENDS
* End of GB01SHT12-CAU SPICE Model
```